

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claims 19 and 28 as follows:

Listing of Claims:

1-18. (Cancelled)

19. (Currently Amended) A method of transferring data between a chip and disposed on a chip package, the chip including memory circuitry having control, address, and data signals, the chip further having bond bonding pads coupled to the memory circuitry to transfer control, address, and data signals to and from the circuitry, the chip package including a plurality of conductive components, the method comprising:

receiving an electronic signal from a bonding pad of the chip;
converting the electronic signal to an electromagnetic signal;
transmitting the electromagnetic signal;
receiving the electromagnetic signal;
converting the received electromagnetic signal to an electronic signal; and
applying the electronic signal to a conductive component of the chip package.

20. (Previously Presented) The method according to claim 19 wherein the operation of transmitting the electromagnetic signal comprises transmitting the electromagnetic signal through an intermediate layer away from chip without the transmission propagating first through the chip.

21. (Previously Presented) The method of claim 20 wherein the operation of transmitting the electromagnetic signal through an intermediate layer comprises transmitting the electromagnetic signal through an adhesive layer having an index of refraction allowing the electromagnetic signal to pass therethrough.

22. (Previously Presented) The method according to claim 20 wherein the operation of transmitting an electromagnetic signal comprises emitting a laser signal.

23. (Previously Presented) The method according to claim 20 wherein the operation of transmitting an electromagnetic signal comprises emitting an optical signal.

24. (Previously Presented) The method according to claim 20 further comprising encapsulating the first surface of the chip package, the chip, and the intermediate layer with an encapsulating layer.

25. (Previously Presented) The method according to claim 19 wherein the operation of transmitting the electromagnetic signal comprises transmitting the electromagnetic signal through the chip itself.

26. (Previously Presented) The method according to claim 25 further comprising coupling the chip to the chip package, wherein the chip comprises a silicon chip;

and further wherein the operation of transmitting an electromagnetic signal comprises emitting an infrared signal.

27. (Previously Presented) The method of claim 25 further comprising encapsulating at least a portion of the chip package and the entire chip with an encapsulating layer.

28. (Currently Amended) A method of transferring data between a chip and disposed on a chip package, the chip including memory circuitry having control, address, and data signals, the chip further having bond bonding pads coupled to the memory circuitry to transfer control, address, and data signals to and from the circuitry, the chip package including a plurality of conductive components, the method comprising:

receiving an electronic signal from a conductive component of the plurality of conductive components;

converting the electronic signal to an electromagnetic signal;
transmitting the electromagnetic signal;
receiving the electromagnetic signal;
converting the received electromagnetic signal to an electronic signal; and
applying the electronic signal to a bonding pad of the chip.

29. (Previously Presented) The method according to claim 28 wherein the operation of transmitting the electromagnetic signal comprises transmitting the electromagnetic signal through an intermediate layer away from chip without the transmission propagating first through the chip.

30. (Previously Presented) The method of claim 29 wherein the operation of transmitting the electromagnetic signal through an intermediate layer comprises transmitting the electromagnetic signal through an adhesive layer having an index of refraction allowing the electromagnetic signal to pass therethrough.

31. (Previously Presented) The method according to claim 29 wherein the operation of transmitting an electromagnetic signal comprises emitting a laser signal.

32. (Previously Presented) The method according to claim 29 wherein the operation of transmitting an electromagnetic signal comprises emitting an optical signal.

33. (Previously Presented) The method according to claim 29 further comprising encapsulating the first surface of the chip package, the chip, and the intermediate layer with an encapsulating layer.

34. (Previously Presented) The method according to claim 28 wherein the operation of transmitting the electromagnetic signal comprises transmitting the electromagnetic signal through the chip itself.

35. (Previously Presented) The method according to claim 34 further comprising coupling the chip to the chip package, wherein the chip comprises a silicon chip; and further wherein the operation of transmitting an electromagnetic signal comprises emitting an infrared signal.

36. (Previously Presented) The method of claim 34 further comprising encapsulating at least a portion of the chip package and the entire chip with an encapsulating layer.

37-54. (Cancelled)